

[54] **PARTICLE FORMATION BY DOUBLE ENCAPSULATION**

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[57]

ABSTRACT

An improved photoelectrophoretic imaging process which comprises placing a suspension of double encapsulated electrically photosensitive particles in an electric field between a pair of surfaces, exposing the suspension to a pattern of electromagnetic radiation and separating the surfaces whereby the exposed portion of the suspension adheres to one surface and the unexposed portion adheres to the other surface. The imaging particles are comprised of a first resin which encapsulates a colorant for the particle and second resin which encapsulates the first resin and contains the electrically photosensitive material.

11 Claims, 1 Drawing Figure

